

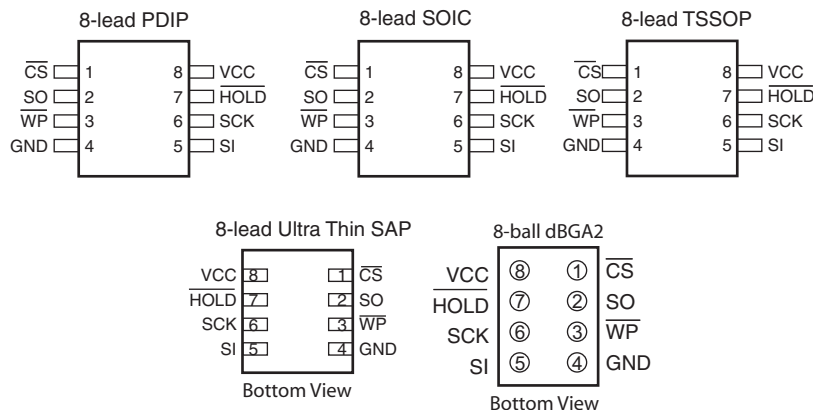
Features

- Serial Peripheral Interface (SPI) Compatible
- Supports SPI Modes 0 (0,0) and 3 (1,1)
- Data Sheet Describes Mode 0 Operation
- Low-voltage and Standard-voltage Operation
 - 2.7 ($V_{CC} = 2.7V$ to 5.5V)
 - 1.8 ($V_{CC} = 1.8V$ to 5.5V)
- 20 MHz Clock Rate (5V)
- 64-byte Page Mode and Byte Write Operation
- Block Write Protection
 - Protect 1/4, 1/2, or Entire Array
- Write Protect (\overline{WP}) Pin and Write Disable Instructions for Both Hardware and Software Data Protection
- Self-timed Write Cycle (5 ms Max)
- High-reliability
 - Endurance: 1 Million Write Cycles
 - Data Retention: >100 Years
- 8-lead PDIP, 8-lead EIAJ SOIC, 8-lead JEDEC SOIC, 8-lead TSSOP, 8-ball dBGAA2 and 8-lead Ultra Thin SAP Packages
- Lead-free/Halogen-free
- Available in Automotive
- Die Sales: Wafer Form, Waffle Pack, and Bumped Die

Description

The AT25128A/256A provides 131,072/262,144 bits of serial electrically-erasable programmable read only memory (EEPROM) organized as 16,384/32,768 words of 8 bits each. The device is optimized for use in many industrial and commercial applications where low-power and low-voltage operation are essential. The devices are available in space saving 8-lead PDIP, 8-lead EIAJ SOIC, 8-lead JEDEC SOIC, 8-lead TSSOP, 8-ball dBGAA2 and 8-lead SAP packages. In addition, the entire family is available in 2.7V (2.7V to 5.5V) and 1.8V (1.8V to 5.5V) versions.

The AT25128A/256A is enabled through the Chip Select pin (\overline{CS}) and accessed via a 3-wire interface consisting of Serial Data Input (SI), Serial Data Output (SO), and Serial Clock (SCK). All programming cycles are completely self-timed, and no separate Erase cycle is required before Write.



SPI Serial EEPROMs

128K (16,384 x 8)

256K (32,768 x 8)

AT25128A AT25256A

**Not
Recommended
for New Design**



Table 0-1. Pin Configurations

| Pin Name | Function |
|-------------------|-----------------------|
| \overline{CS} | Chip Select |
| SCK | Serial Data Clock |
| SI | Serial Data Input |
| SO | Serial Data Output |
| GND | Ground |
| VCC | Power Supply |
| \overline{WP} | Write Protect |
| \overline{HOLD} | Suspends Serial Input |
| NC | No Connect |

Block Write protection is enabled by programming the status register with top ¼, top ½ or entire array of write protection. Separate Program Enable and Program Disable instructions are provided for additional data protection. Hardware data protection is provided via the \overline{WP} pin to protect against inadvertent write attempts to the status register. The \overline{HOLD} pin may be used to suspend any serial communication without resetting the serial sequence.

1. Absolute Maximum Ratings*

| | |
|---|-----------------|
| Operating Temperature | -55°C to +125°C |
| Storage Temperature..... | -65°C to +150°C |
| Voltage on Any Pin with Respect to Ground..... | -1.0V to +7.0V |
| Maximum Operating Voltage | 6.25V |
| DC Output Current..... | 5.0 mA |

*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 1-1. Block Diagram

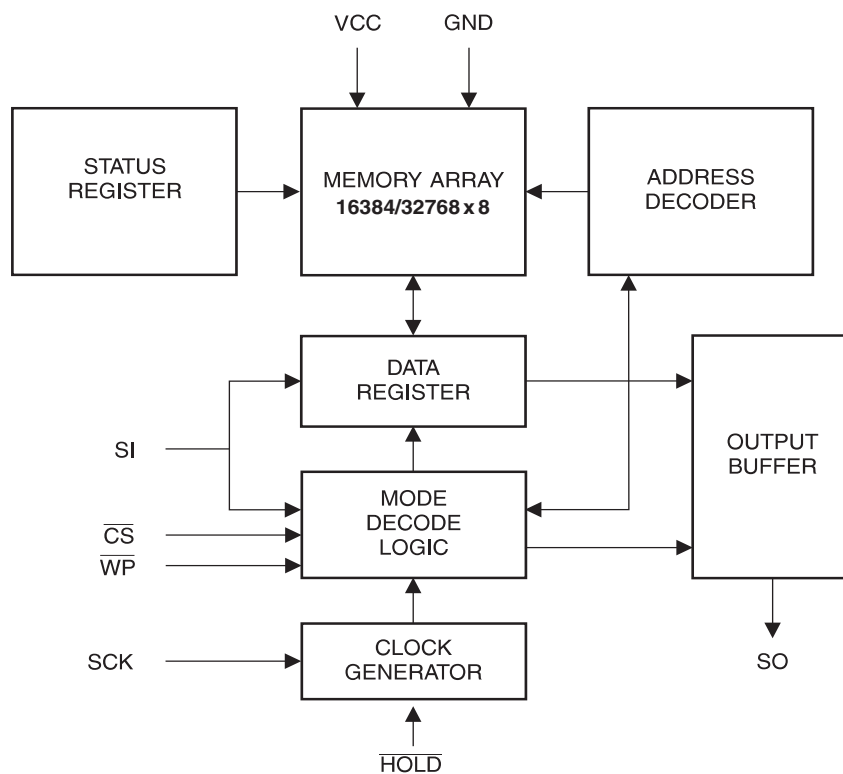


Table 1-1. Pin Capacitance⁽¹⁾

Applicable over recommended operating range from $T_A = 25^\circ\text{C}$, $f = 1.0\text{ MHz}$, $V_{CC} = +5.0\text{V}$ (unless otherwise noted)

| Symbol | Test Conditions | Max | Units | Conditions |
|-----------|--|-----|-------|-----------------------|
| C_{OUT} | Output Capacitance (SO) | 8 | pF | $V_{OUT} = 0\text{V}$ |
| C_{IN} | Input Capacitance (\overline{CS} , SCK, SI, \overline{WP} , \overline{HOLD}) | 6 | pF | $V_{IN} = 0\text{V}$ |

Note: 1. This parameter is characterized and is not 100% tested.

Table 1-2. DC Characteristics

Applicable over recommended operating range from $T_{AI} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{CC} = +1.8\text{V}$ to $+5.5\text{V}$,
 $T_{AE} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $V_{CC} = +1.8\text{V}$ to $+5.5\text{V}$ (unless otherwise noted)

| Symbol | Parameter | Test Condition | Min | Typ | Max | Units |
|----------------|---------------------|---|---------------------------|------------------------------------|---------------------|---------------|
| V_{CC1} | Supply Voltage | | 1.8 | | 5.5 | V |
| V_{CC2} | Supply Voltage | | 2.7 | | 5.5 | V |
| V_{CC3} | Supply Voltage | | 4.5 | | 5.5 | V |
| I_{CC1} | Supply Current | $V_{CC} = 5.0\text{V}$ at 20 MHz, SO = Open, Read | | 9.0 | 10.0 | mA |
| I_{CC2} | Supply Current | $V_{CC} = 5.0\text{V}$ at 10 MHz, SO = Open, Read, Write | | 5.0 | 7.0 | mA |
| I_{CC3} | Supply Current | $V_{CC} = 5.0\text{V}$ at 1 MHz, SO = Open, Read, Write | | 2.2 | 3.5 | mA |
| I_{SB1} | Standby Current | $V_{CC} = 1.8\text{V}$, $\overline{CS} = V_{CC}$ | | 0.2 | 3.0 | μA |
| I_{SB2} | Standby Current | $V_{CC} = 2.7\text{V}$, $\overline{CS} = V_{CC}$ | | 0.5 | 3.0 | μA |
| I_{SB3} | Standby Current | $V_{CC} = 5.0\text{V}$, $\overline{CS} = V_{CC}$ | | 2.0 | 5.0 | μA |
| I_{IL} | Input Leakage | $V_{IN} = 0\text{V}$ to V_{CC} | -3.0 | | 3.0 | μA |
| I_{OL} | Output Leakage | $V_{IN} = 0\text{V}$ to V_{CC} , $T_{AC} = 0^{\circ}\text{C}$ to 70°C | -3.0 | | 3.0 | μA |
| $V_{IL}^{(1)}$ | Input Low-voltage | | -1.0 | | $V_{CC} \times 0.3$ | V |
| $V_{IH}^{(1)}$ | Input High-voltage | | $V_{CC} \times 0.7$ | | $V_{CC} + 0.5$ | V |
| V_{OL1} | Output Low-voltage | $3.6 \leq V_{CC} \leq 5.5\text{V}$ | | | 0.4 | V |
| V_{OH1} | Output High-voltage | | $I_{OL} = 3.0\text{ mA}$ | $I_{OH} = -1.6\text{ mA}$ | $V_{CC} - 0.8$ | V |
| V_{OL2} | Output Low-voltage | $1.8\text{V} \leq V_{CC} \leq 3.6\text{V}$ | | | 0.2 | V |
| V_{OH2} | Output High-voltage | | $I_{OL} = 0.15\text{ mA}$ | $I_{OH} = -100\text{ }\mu\text{A}$ | $V_{CC} - 0.2$ | V |

Note: 1. V_{IL} min and V_{IH} max are reference only and are not tested.

Table 1-3. AC Characteristics

Applicable over recommended operating range from $T_{AI} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $T_{AE} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $V_{CC} = \text{As Specified}$, $CL = 1$ TTL Gate and 30 pF (unless otherwise noted)

| Symbol | Parameter | Voltage | Min | Max | Units |
|-----------|--|---------|-----|-----|---------------|
| f_{SCK} | SCK Clock Frequency | 4.5–5.5 | 0 | 20 | MHz |
| | | 2.7–5.5 | 0 | 10 | |
| | | 1.8–5.5 | 0 | 5 | |
| t_{RI} | Input Rise Time | 4.5–5.5 | | 2 | μs |
| | | 2.7–5.5 | | 2 | |
| | | 1.8–5.5 | | 2 | |
| t_{FI} | Input Fall Time | 4.5–5.5 | | 2 | μs |
| | | 2.7–5.5 | | 2 | |
| | | 1.8–5.5 | | 2 | |
| t_{WH} | SCK High Time | 4.5–5.5 | 20 | | ns |
| | | 2.7–5.5 | 40 | | |
| | | 1.8–5.5 | 80 | | |
| t_{WL} | SCK Low Time | 4.5–5.5 | 20 | | ns |
| | | 2.7–5.5 | 40 | | |
| | | 1.8–5.5 | 80 | | |
| t_{CS} | \overline{CS} High Time | 4.5–5.5 | 100 | | ns |
| | | 2.7–5.5 | 100 | | |
| | | 1.8–5.5 | 200 | | |
| t_{CSS} | \overline{CS} Setup Time | 4.5–5.5 | 100 | | ns |
| | | 2.7–5.5 | 100 | | |
| | | 1.8–5.5 | 200 | | |
| t_{CSH} | \overline{CS} Hold Time | 4.5–5.5 | 100 | | ns |
| | | 2.7–5.5 | 100 | | |
| | | 1.8–5.5 | 200 | | |
| t_{SU} | Data In Setup Time | 4.5–5.5 | 5 | | ns |
| | | 2.7–5.5 | 10 | | |
| | | 1.8–5.5 | 20 | | |
| t_H | Data In Hold Time | 4.5–5.5 | 5 | | ns |
| | | 2.7–5.5 | 10 | | |
| | | 1.8–5.5 | 20 | | |
| t_{HD} | $\overline{\text{Hold}}$ Setup Time | 4.5–5.5 | 5 | | ns |
| | | 2.7–5.5 | 10 | | |
| | | 1.8–5.5 | 20 | | |
| t_{CD} | $\overline{\text{Hold}}$ Hold Time | 4.5–5.5 | 5 | | ns |
| | | 2.7–5.5 | 10 | | |
| | | 1.8–5.5 | 20 | | |
| t_V | Output Valid | 4.5–5.5 | 0 | 20 | ns |
| | | 2.7–5.5 | 0 | 40 | |
| | | 1.8–5.5 | 0 | 80 | |
| t_{HO} | Output Hold Time | 4.5–5.5 | 0 | | ns |
| | | 2.7–5.5 | 0 | | |
| | | 1.8–5.5 | 0 | | |
| t_{LZ} | $\overline{\text{Hold}}$ to Output Low Z | 4.5–5.5 | 0 | 25 | ns |
| | | 2.7–5.5 | 0 | 50 | |
| | | 1.8–5.5 | 0 | 100 | |

Table 1-3. AC Characteristics (Continued)

Applicable over recommended operating range from $T_{AI} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $T_{AE} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $V_{CC} = \text{As Specified}$, $CL = 1$ TTL Gate and 30 pF (unless otherwise noted)

| Symbol | Parameter | Voltage | Min | Max | Units |
|--------------------------|-----------------------|-------------------------------|-----|-----------------|--------------|
| t_{HZ} | Hold to Output High Z | 4.5–5.5 2.7–5.5 1.8–5.5 | | 25 50 100 | ns |
| t_{DIS} | Output Disable Time | 4.5–5.5 2.7–5.5 1.8–5.5 | | 25 50 100 | ns |
| t_{WC} | Write Cycle Time | 4.5–5.5 2.7–5.5 1.8–5.5 | | 5 5 5 | ms |
| Endurance ⁽¹⁾ | 5.0V, 25°C, Page Mode | | 1M | | Write Cycles |

Notes: 1. This parameter is characterized and is not 100% tested. Contact Atmel for further information.

2. Serial Interface Description

MASTER: The device that generates the serial clock.

SLAVE: Because the serial clock pin (SCK) is always an input, the AT25128A/256A always operates as a slave.

TRANSMITTER/RECEIVER: The AT25128A/256A has separate pins designated for data transmission (SO) and reception (SI).

MSB: The Most Significant Bit (MSB) is the first bit transmitted and received.

SERIAL OP-CODE: After the device is selected with \overline{CS} going low, the first byte will be received. This byte contains the op-code that defines the operations to be performed.

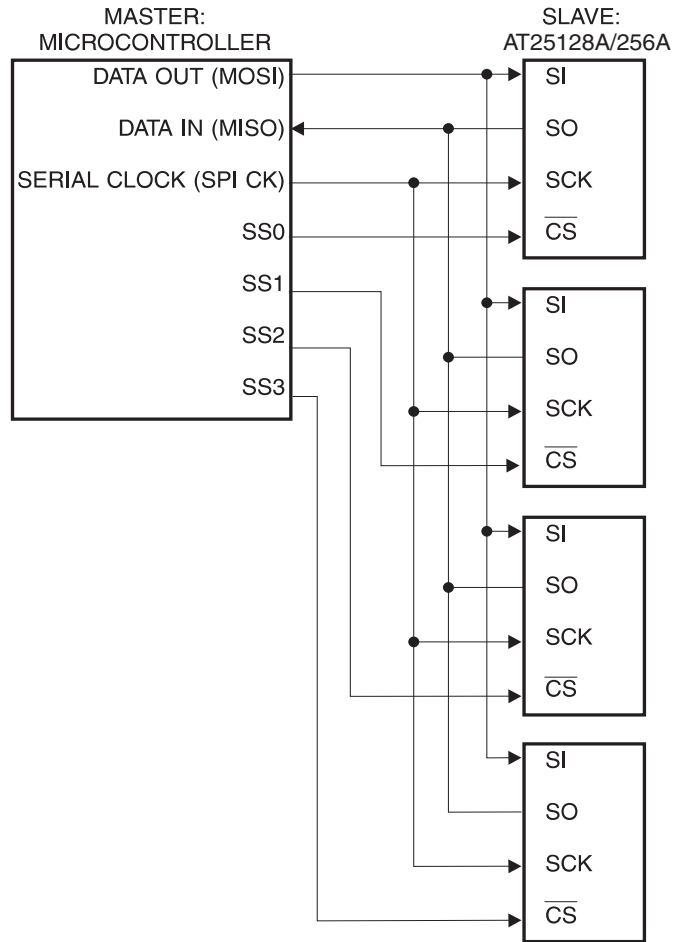
INVALID OP-CODE: If an invalid op-code is received, no data will be shifted into the AT25128A/256A, and the serial output pin (SO) will remain in a high impedance state until the falling edge of \overline{CS} is detected again. This will reinitialize the serial communication.

CHIP SELECT: The AT25128A/256A is selected when the \overline{CS} pin is low. When the device is not selected, data will not be accepted via the SI pin, and the serial output pin (SO) will remain in a high impedance state.

HOLD: The \overline{HOLD} pin is used in conjunction with the \overline{CS} pin to select the AT25128A/256A. When the device is selected and a serial sequence is underway, \overline{HOLD} can be used to pause the serial communication with the master device without resetting the serial sequence. To pause, the \overline{HOLD} pin must be brought low while the SCK pin is low. To resume serial communication, the \overline{HOLD} pin is brought high while the SCK pin is low (SCK may still toggle during \overline{HOLD}). Inputs to the SI pin will be ignored while the SO pin is in the high impedance state.

WRITE PROTECT: The write protect pin (\overline{WP}) will allow normal read/write operations when held high. When the \overline{WP} pin is brought low and WPEN bit is "1", all write operations to the status register are inhibited. \overline{WP} going low while \overline{CS} is still low will interrupt a write to the status register. If the internal write cycle has already been initiated, \overline{WP} going low will have no effect on any write operation to the status register. The \overline{WP} pin function is blocked when the WPEN bit in the status register is "0". This will allow the user to install the AT25128A/256A in a system with the \overline{WP} pin tied to ground and still be able to write to the status register. All \overline{WP} pin functions are enabled when the WPEN bit is set to "1".

Figure 2-1. SPI Serial Interface



3. Functional Description

The AT25128A/256A is designed to interface directly with the synchronous serial peripheral interface (SPI) of the 6800 type series of microcontrollers.

The AT25128A/256A utilizes an 8-bit instruction register. The list of instructions and their operation codes are contained in see [Table 4-3](#). All instructions, addresses, and data are transferred with the MSB first and start with a high-to-low \overline{CS} transition.

Table 3-1. Instruction Set for the AT25128A/256A

| Instruction Name | Instruction Format | Operation |
|------------------|--------------------|-----------------------------|
| WREN | 0000 X110 | Set Write Enable Latch |
| WRDI | 0000 X100 | Reset Write Enable Latch |
| RDSR | 0000 X101 | Read Status Register |
| WRSR | 0000 X001 | Write Status Register |
| READ | 0000 X011 | Read Data from Memory Array |
| WRITE | 0000 X010 | Write Data to Memory Array |

WRITE ENABLE (WREN): The device will power-up in the write disable state when V_{CC} is applied. All programming instructions must therefore be preceded by a Write Enable instruction.

WRITE DISABLE (WRDI): To protect the device against inadvertent writes, the Write Disable instruction disables all programming modes. The WRDI instruction is independent of the status of the \overline{WP} pin.

READ STATUS REGISTER (RDSR): The Read Status Register instruction provides access to the status register. The Ready/Busy and Write Enable status of the device can be determined by the RDSR instruction. Similarly, the Block Write Protection bits indicate the extent of protection employed. These bits are set by using the WRSR instruction.

Table 3-2. Status Register Format

| Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 |
|-------|-------|-------|-------|-------|-------|-------|------------------|
| WPEN | X | X | X | BP1 | BP0 | WEN | \overline{RDY} |

Table 3-3. Read Status Register Bit Definition

| Bit | Definition |
|--|--|
| Bit 0 (\overline{RDY}) | Bit 0 = "0" (\overline{RDY}) indicates the device is ready. Bit 0 = "1" indicates the write cycle is in progress. |
| Bit 1 (WEN) | Bit 1 = 0 indicates the device <i>is not</i> write enabled. Bit 1 = "1" indicates the device is write enabled. |
| Bit 2 (BP0) | See Table 3-4 on page 10 . |
| Bit 3 (BP1) | See Table 3-4 on page 10 . |
| Bits 4 – 6 are 0s when device is not in an internal write cycle. | |
| Bit 7 (WPEN) | See Table 3-5 on page 10 . |
| Bits 0 – 7 are "1"s during an internal write cycle. | |

WRITE STATUS REGISTER (WRSR): The WRSR instruction allows the user to select one of four levels of protection. The AT25128A/256A is divided into four array segments. Top quarter (1/4), top half (1/2), or all of the memory segments can be protected. Any of the data within any selected segment will therefore be read only. The block write protection levels and corresponding status register control bits are shown in Table 3-4.

The three bits, BP0, BP1, and WPEN are nonvolatile cells that have the same properties and functions as the regular memory cells (e.g. WREN, t_{WC} , RDSR).

Table 3-4. Block Write Protect Bits

| Level | Status Register Bits | | Array Addresses Protected | |
|--------|----------------------|-----|---------------------------|-------------|
| | BP1 | BP0 | AT25128A | AT25256A |
| 0 | 0 | 0 | None | None |
| 1(1/4) | 0 | 1 | 3000 – 3FFF | 6000 – 7FFF |
| 2(1/2) | 1 | 0 | 2000 – 3FFF | 4000 – 7FFF |
| 3(All) | 1 | 1 | 0000 – 3FFF | 0000 – 7FFF |

The WRSR instruction also allows the user to enable or disable the write protect (\overline{WP}) pin through the use of the write protect enable (WPEN) bit. Hardware write protection is enabled when the \overline{WP} pin is low and the WPEN bit is “1”. Hardware write protection is disabled when *either* the \overline{WP} pin is high or the WPEN bit is “0”. When the device is hardware write protected, writes to the Status Register, including the Block Protect bits and the WPEN bit, and the block-protected sections in the memory array are disabled. Writes are only allowed to sections of the memory which are not block-protected.

NOTE: When the WPEN bit is hardware write protected, it cannot be changed back to “0”, as long as the \overline{WP} pin is held low.

Table 3-5. WPEN Operation

| WPEN | WP | WEN | Protected Blocks | Unprotected Blocks | Status Register |
|------|------|-----|------------------|--------------------|-----------------|
| 0 | X | 0 | Protected | Protected | Protected |
| 0 | X | 1 | Protected | Writable | Writable |
| 1 | Low | 0 | Protected | Protected | Protected |
| 1 | Low | 1 | Protected | Writable | Protected |
| X | High | 0 | Protected | Protected | Protected |
| X | High | 1 | Protected | Writable | Writable |

READ SEQUENCE (READ): Reading the AT25128A/256A via the SO pin requires the following sequence. After the \overline{CS} line is pulled low to select a device, the Read op-code is transmitted via the SI line followed by the byte address to be read (see Table 3-6 on page 11). Upon completion, any data on the SI line will be ignored. The data (D7 - D0) at the specified address is then shifted out onto the SO line. If only one byte is to be read, the \overline{CS} line should be driven high after the data comes out. The read sequence can be continued since the byte address is automatically incremented and data will continue to be shifted out. When the highest address is

reached, the address counter will roll over to the lowest address allowing the entire memory to be read in one continuous read cycle.

WRITE SEQUENCE (WRITE): In order to program the AT25128A/256A, two separate instructions must be executed. First, the device *must be write enabled* via the Write Enable (WREN) Instruction. Then a Write instruction may be executed. Also, the address of the memory location(s) to be programmed must be outside the protected address field location selected by the Block Write Protection Level. During an internal write cycle, all commands will be ignored except the RDSR instruction.

A Write Instruction requires the following sequence. After the \overline{CS} line is pulled low to select the device, the Write op-code is transmitted via the SI line followed by the byte address and the data (D7 - D0) to be programmed (see Table 3-6). Programming will start after the \overline{CS} pin is brought high. (The Low-to-High transition of the \overline{CS} pin must occur during the SCK low time immediately after clocking in the D0 (LSB) data bit.

The Ready/Busy status of the device can be determined by initiating a Read Status Register (RDSR) Instruction. If Bit 0 = 1, the Write cycle is still in progress. If Bit 0 = 0, the Write cycle has ended. Only the Read Status Register instruction is enabled during the Write programming cycle.

The AT25128A/256A is capable of a 64-byte Page Write operation. After each byte of data is received, the six low order address bits are internally incremented by one; the high order bits of the address will remain constant. If more than 64 bytes of data are transmitted, the address counter will roll over and the previously written data will be overwritten. The AT25128A/256A is automatically returned to the write disable state at the completion of a Write cycle.

NOTE: If the device is not write enabled (WREN), the device will ignore the Write instruction and will return to the standby state, when \overline{CS} is brought high. A new CS falling edge is required to re-initiate the serial communication.

Table 3-6. Address Key

| Address | AT25128A | AT25256A |
|-----------------|-------------------|----------------|
| A_N | $A_{13} - A_0$ | $A_{14} - A_0$ |
| Don't Care Bits | $A_{15} - A_{14}$ | A_{15} |

4. Timing Diagrams (for SPI Mode 0 (0, 0))

Figure 4-1. Synchronous Data Timing

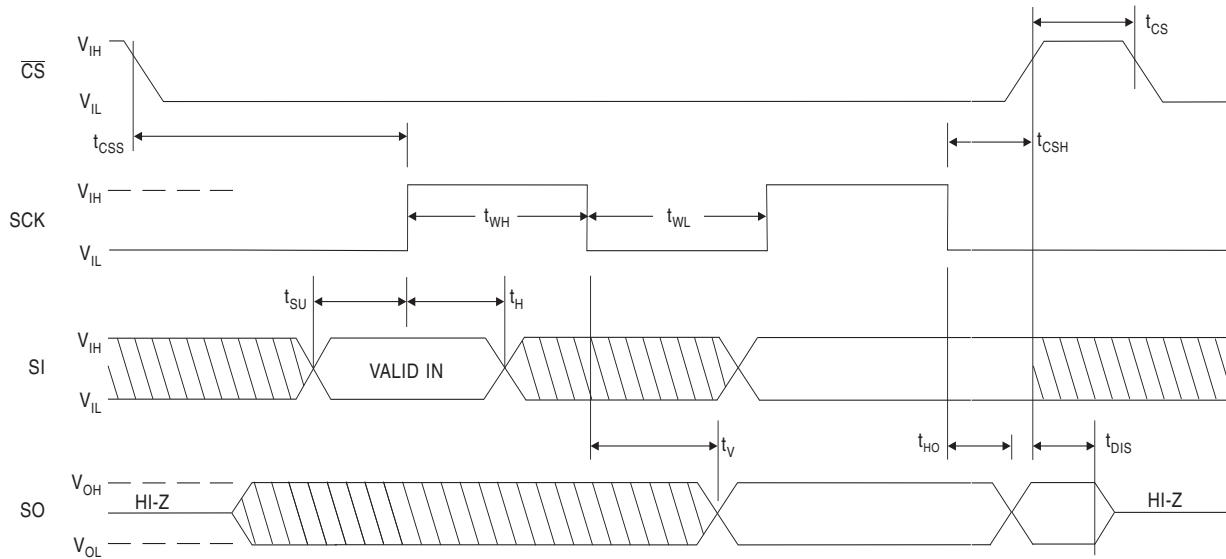


Figure 4-2. WREN Timing

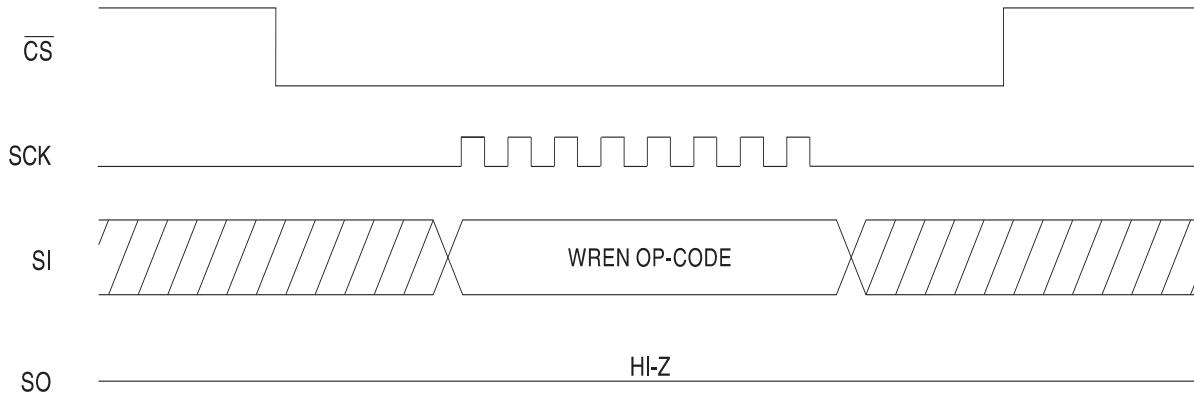


Figure 4-3. WRDI Timing

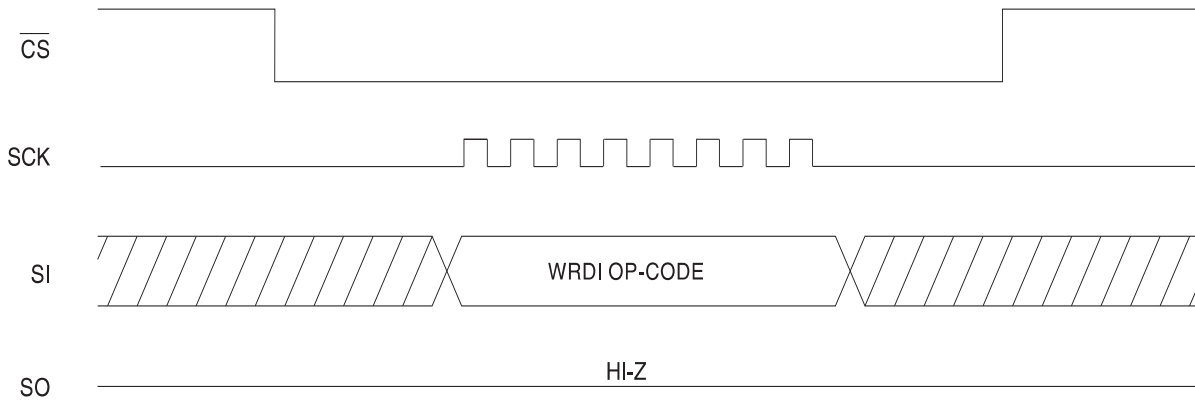


Figure 4-4. RDSR Timing

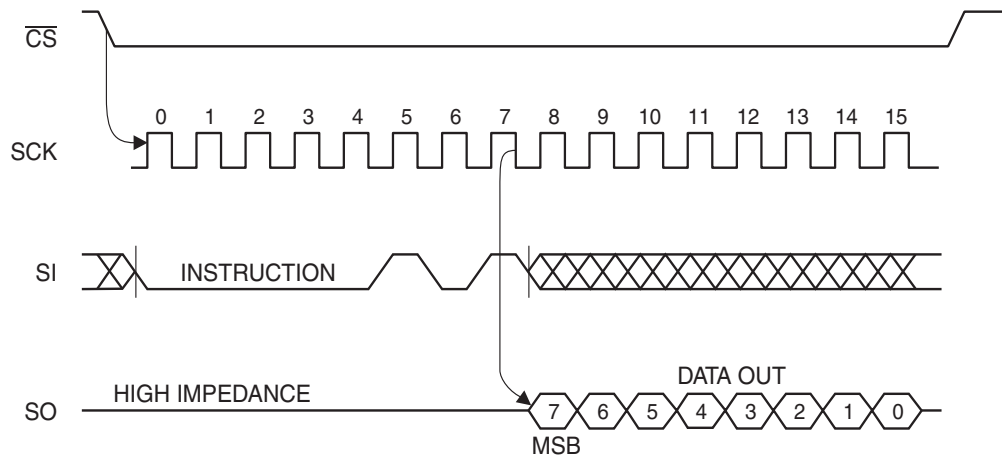


Figure 4-5. WRSR Timing

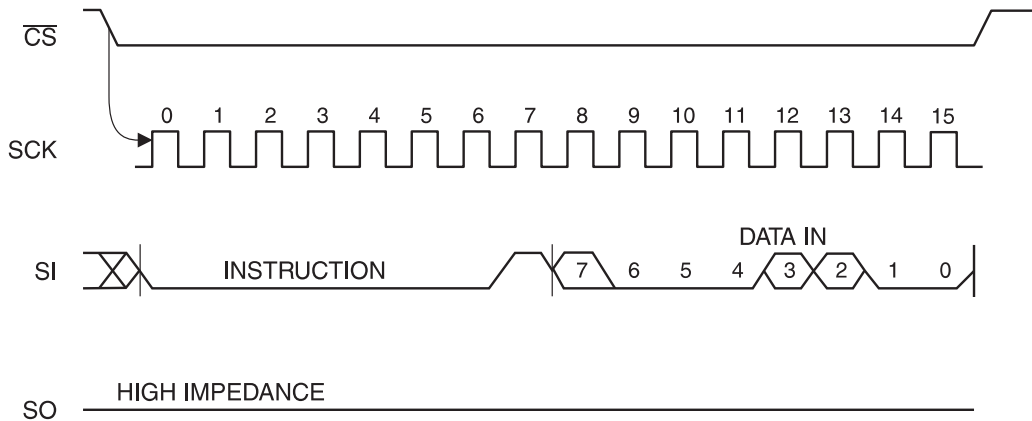


Figure 4-6. READ Timing

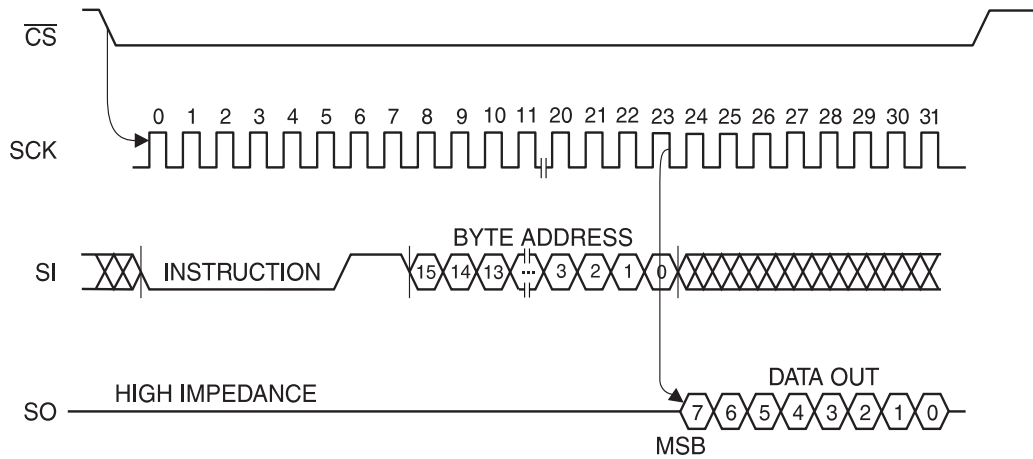


Figure 4-7. WRITE Timing

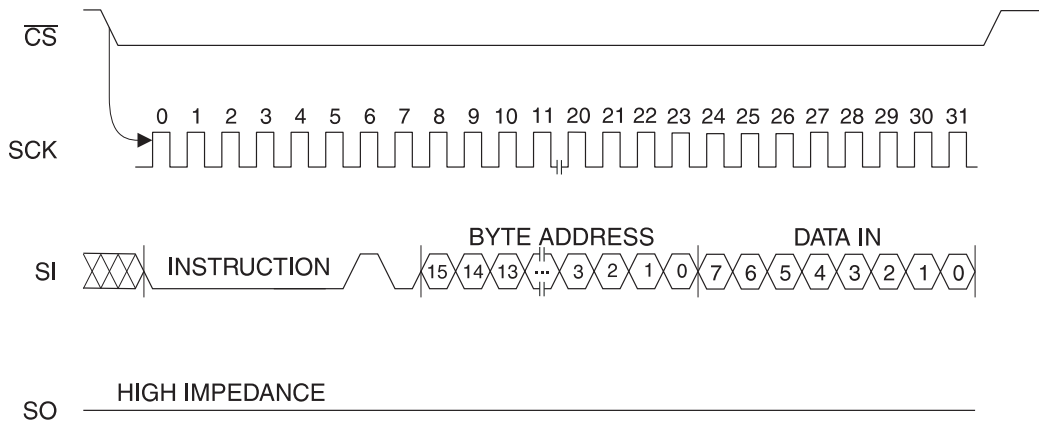
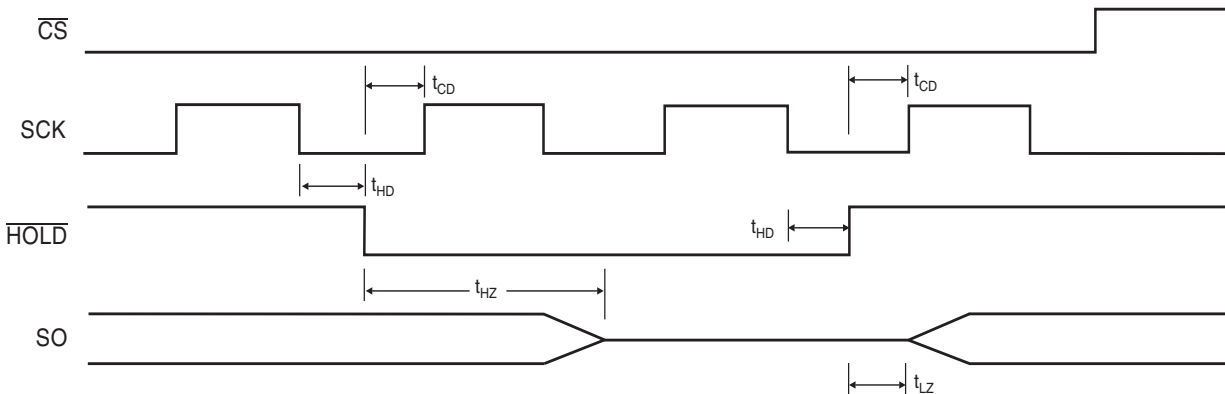


Figure 4-8. HOLD Timing



5. AT25128A Ordering Information⁽¹⁾

| Ordering Code | Package | Operation Range |
|------------------------------------|----------|--|
| AT25128A-10PU-2.7 ⁽²⁾ | 8P3 | Lead-free/Halogen-free/ Industrial Temperature (-40°C to 85°C) |
| AT25128A-10PU-1.8 ⁽²⁾ | 8P3 | |
| AT25128AN-10SU-2.7 ⁽²⁾ | 8S1 | |
| AT25128AN-10SU-1.8 ⁽²⁾ | 8S1 | |
| AT25128AW-10SU-2.7 ⁽²⁾ | 8S2 | |
| AT25128AW-10SU-1.8 ⁽²⁾ | 8S2 | |
| AT25128A-10TU-2.7 ⁽²⁾ | 8A2 | |
| AT25128A-10TU-1.8 ⁽²⁾ | 8A2 | |
| AT25128AU2-10UU-1.8 ⁽²⁾ | 8U2-1 | |
| AT25128AY7-10YH-1.8 ⁽²⁾ | 8Y7 | |
| AT25128A-W1.8-11 ⁽³⁾ | Die Sale | Industrial Temperature (-40°C to 85°C) |

- Notes:
1. For 2.7V devices used in the 4.5V to 5.5V range, please refer to performance values in the AC and DC Characteristics tables.
 2. "U" designates Green package + RoHS compliant.
 3. Available in waffle pack and wafer form; order as SL788 for wafer form. Bumped die available upon request. Please Contact Serial Interface Marketing.

| Package Type | |
|--------------|---|
| 8P3 | 8-lead, 0.300" Wide, Plastic Dual In-line Package (PDIP) |
| 8S1 | 8-lead, 0.150" Wide, Plastic Gull Wing Small Outline Package (JEDEC SOIC) |
| 8S2 | 8-lead, 0.200" Wide, Plastic Gull Wing Small Outline Package (EIAJ SOIC) |
| 8U2-1 | 8-ball, die Ball Grid Array Package (dBGA2) |
| 8A2 | 8-lead, 4.4 mm Body, Thin Shrink Small Outline Package (TSSOP) |
| 8Y7 | 8-lead, 6.00 mm x 4.90 mm Body, Ultra Thin, Dual Footprint, Non-leaded, Small Array Package (SAP) |
| Options | |
| -2.7 | Low-voltage (2.7V to 5.5V) |
| -1.8 | Low-voltage (1.8V to 5.5V) |



AT25256A Ordering Information⁽¹⁾

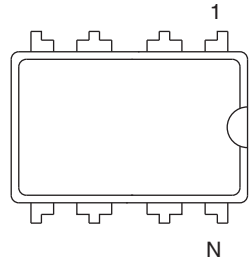
| Ordering Code | Package | Operation Range |
|------------------------------------|----------|--|
| AT25256A-10PU-2.7 ⁽²⁾ | 8P3 | Lead-free/Halogen-free/ Industrial Temperature (-40°C to 85°C) |
| AT25256A-10PU-1.8 ⁽²⁾ | 8P3 | |
| AT25256AN-10SU-2.7 ⁽²⁾ | 8S1 | |
| AT25256AN-10SU-1.8 ⁽²⁾ | 8S1 | |
| AT25256AW-10SU-2.7 ⁽²⁾ | 8S2 | |
| AT25256AW-10SU-1.8 ⁽²⁾ | 8S2 | |
| AT25256A-10TU-2.7 ⁽²⁾ | 8A2 | |
| AT25256A-10TU-1.8 ⁽²⁾ | 8A2 | |
| AT25256AU2-10UU-1.8 ⁽²⁾ | 8U2-1 | |
| AT25256AY7-10YH-1.8 ⁽²⁾ | 8Y7 | |
| AT25256A-W1.8-11 ⁽³⁾ | Die Sale | Industrial Temperature (-40°C to 85°C) |

- Notes:
1. For 2.7V devices used in the 4.5V to 5.5V range, please refer to performance values in the AC and DC Characteristics tables.
 2. "U" designates Green package + RoHS compliant.
 3. Available in wafer pack and wafer form; order as SL788 for wafer form. Bumped die available upon request. Please contact Serial Interface Marketing.

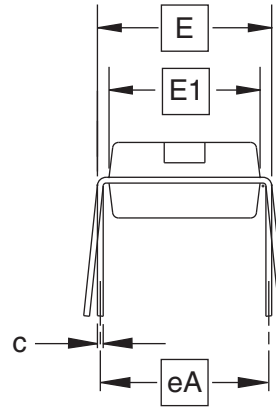
| Package Type | |
|--------------|---|
| 8P3 | 8-lead, 0.300" Wide, Plastic Dual In-line Package (PDIP) |
| 8S1 | 8-lead, 0.150" Wide, Plastic Gull Wing Small Outline Package (JEDEC SOIC) |
| 8S2 | 8-lead, 0.200" Wide, Plastic Gull Wing Small Outline Package (EIAJ SOIC) |
| 8U2-1 | 8-ball, die Ball Grid Array Package (dBGAA2) |
| 8A2 | 8-lead, 4.4 mm Body, Thin Shrink Small Outline Package (TSSOP) |
| 8Y7 | 8-lead, 6.00 mm x 4.90 mm Body, Ultra Thin, Dual Footprint, Non-leaded, Small Array Package (SAP) |
| Options | |
| -2.7 | Low-voltage (2.7V to 5.5V) |
| -1.8 | Low-voltage (1.8V to 5.5V) |

6. Packaging Information

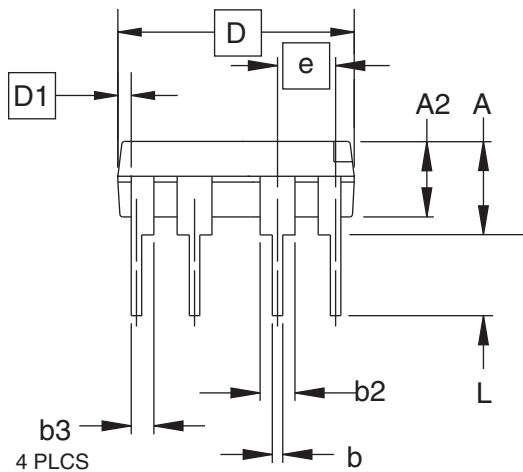
8P3 – PDIP



Top View



End View



Side View

COMMON DIMENSIONS
(Unit of Measure = inches)

| SYMBOL | MIN | NOM | MAX | NOTE |
|--------|-----------|-------|-------|------|
| A | – | – | 0.210 | 2 |
| A2 | 0.115 | 0.130 | 0.195 | |
| b | 0.014 | 0.018 | 0.022 | 5 |
| b2 | 0.045 | 0.060 | 0.070 | 6 |
| b3 | 0.030 | 0.039 | 0.045 | 6 |
| c | 0.008 | 0.010 | 0.014 | |
| D | 0.355 | 0.365 | 0.400 | 3 |
| D1 | 0.005 | – | – | 3 |
| E | 0.300 | 0.310 | 0.325 | 4 |
| E1 | 0.240 | 0.250 | 0.280 | 3 |
| e | 0.100 BSC | | | |
| eA | 0.300 BSC | | | 4 |
| L | 0.115 | 0.130 | 0.150 | 2 |

- Notes:
1. This drawing is for general information only; refer to JEDEC Drawing MS-001, Variation BA, for additional information.
 2. Dimensions A and L are measured with the package seated in JEDEC seating plane Gauge GS-3.
 3. D, D1 and E1 dimensions do not include mold Flash or protrusions. Mold Flash or protrusions shall not exceed 0.010 inch.
 4. E and eA measured with the leads constrained to be perpendicular to datum.
 5. Pointed or rounded lead tips are preferred to ease insertion.
 6. b2 and b3 maximum dimensions do not include Dambar protrusions. Dambar protrusions shall not exceed 0.010 (0.25 mm).

01/09/02

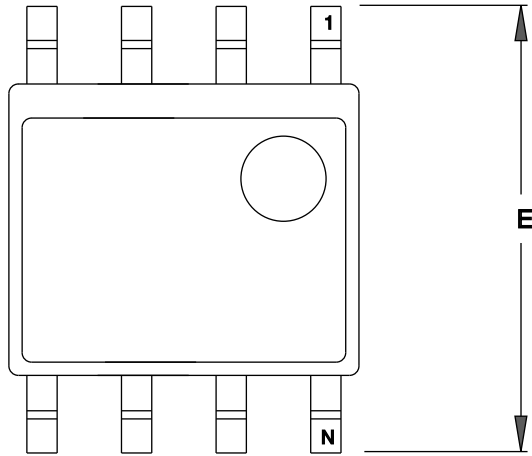
ATMEL 2325 Orchard Parkway
San Jose, CA 95131

TITLE
8P3, 8-lead, 0.300" Wide Body, Plastic Dual
In-line Package (PDIP)

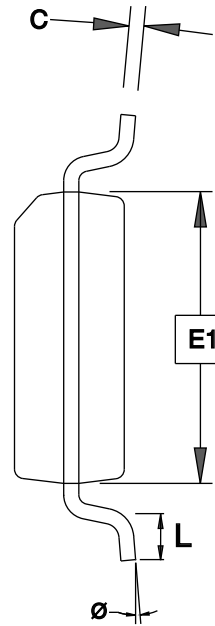
DRAWING NO.
8P3

REV.
B

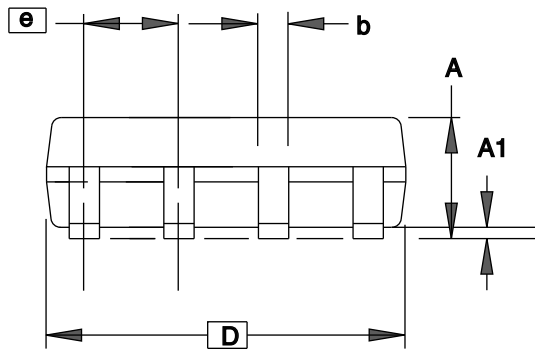
8S1 – JEDEC SOIC



TOP VIEW



END VIEW



SIDE VIEW

COMMON DIMENSIONS
(Unit of Measure = mm)

| SYMBOL | MIN | NOM | MAX | NOTE |
|--------|----------|-----|------|------|
| A | 1.35 | – | 1.75 | |
| A1 | 0.10 | – | 0.25 | |
| b | 0.31 | – | 0.51 | |
| C | 0.17 | – | 0.25 | |
| D | 4.80 | – | 5.05 | |
| E1 | 3.81 | – | 3.99 | |
| E | 5.79 | – | 6.20 | |
| e | 1.27 BSC | | | |
| L | 0.40 | – | 1.27 | |
| θ | 0° | – | 8° | |

Note: These drawings are for general information only. Refer to JEDEC Drawing MS-012, Variation AA for proper dimensions, tolerances, datums, etc.

3/17/05



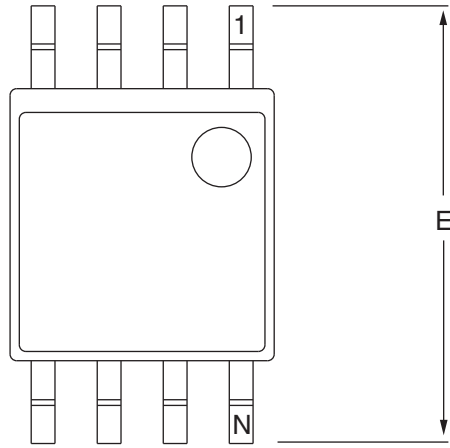
1150 E. Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906

TITLE
8S1, 8-lead (0.150" Wide Body), Plastic Gull Wing
Small Outline (JEDEC SOIC)

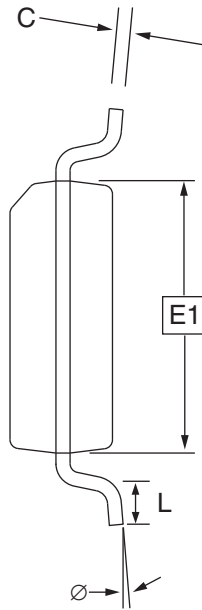
DRAWING NO.
8S1

REV.
C

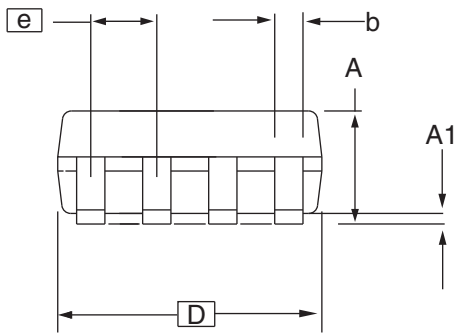
8S2 – EIAJ SOIC



Top View



End View



Side View

COMMON DIMENSIONS
(Unit of Measure = mm)

| SYMBOL | MIN | NOM | MAX | NOTE |
|--------|----------|-----|------|------|
| A | 1.70 | | 2.16 | |
| A1 | 0.05 | | 0.25 | |
| b | 0.35 | | 0.48 | 5 |
| C | 0.15 | | 0.35 | 5 |
| D | 5.13 | | 5.35 | |
| E1 | 5.18 | | 5.40 | 2, 3 |
| E | 7.70 | | 8.26 | |
| L | 0.51 | | 0.85 | |
| Ø | 0° | | 8° | |
| e | 1.27 BSC | | | 4 |

- Notes: 1. This drawing is for general information only; refer to EIAJ Drawing EDR-7320 for additional information.
 2. Mismatch of the upper and lower dies and resin burrs are not included.
 3. It is recommended that upper and lower cavities be equal. If they are different, the larger dimension shall be regarded.
 4. Determines the true geometric position.
 5. Values b and C apply to pb/Sn solder plated terminal. The standard thickness of the solder layer shall be 0.010 +0.010/-0.005 mm.

10/7/03



2325 Orchard Parkway
San Jose, CA 95131

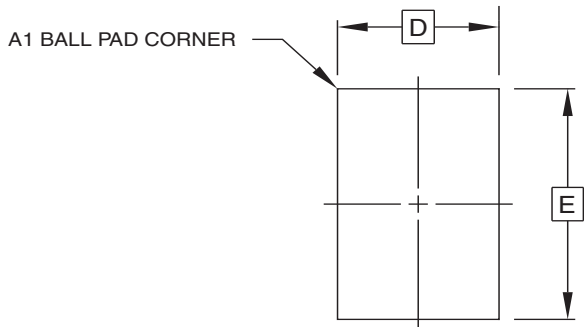
TITLE
8S2, 8-lead, 0.209" Body, Plastic Small
Outline Package (EIAJ)

DRAWING NO.
8S2

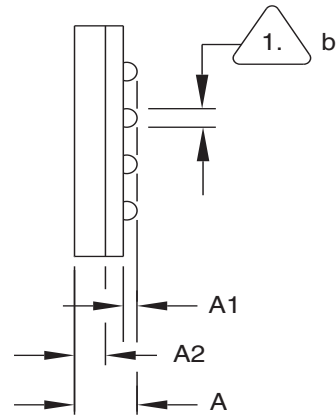
REV.
C



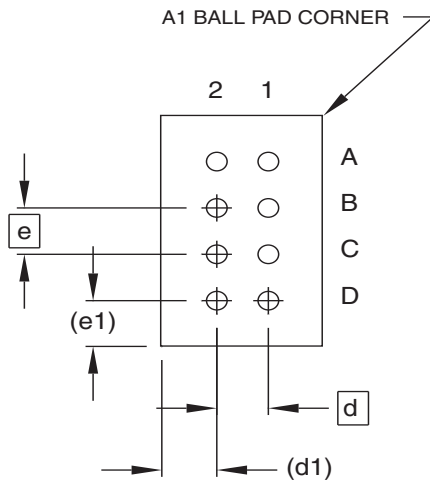
8U2-1 – dBGA2



Top View



Side View



Bottom View
8 Solder Balls

COMMON DIMENSIONS
(Unit of Measure = mm)

| SYMBOL | MIN | NOM | MAX | NOTE |
|--------|----------|------|------|------|
| A | 0.81 | 0.91 | 1.00 | |
| A1 | 0.15 | 0.20 | 0.25 | |
| A2 | 0.40 | 0.45 | 0.50 | |
| b | 0.25 | 0.30 | 0.35 | 1 |
| D | 2.35 BSC | | | |
| E | 3.73 BSC | | | |
| e | 0.75 BSC | | | |
| e1 | 0.74 REF | | | |
| d | 0.75 BSC | | | |
| d1 | 0.80 REF | | | |

1. Dimension 'b' is measured at the maximum solder ball diameter.

This drawing is for general information only.

6/24/03



1150 E. Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906

TITLE

8U2-1, 8-ball, 2.35 x 3.73 mm Body, 0.75 mm pitch,
Small Die Ball Grid Array Package (dBGA2)

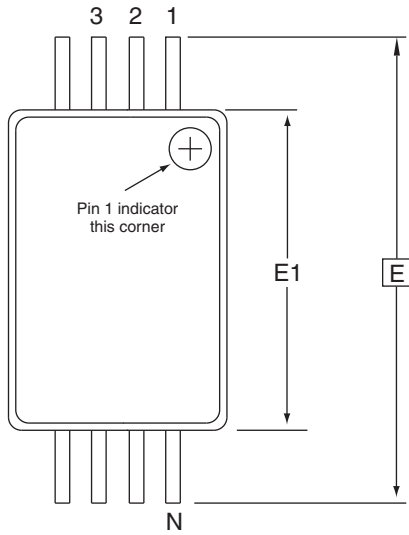
DRAWING NO.

PO8U2-1

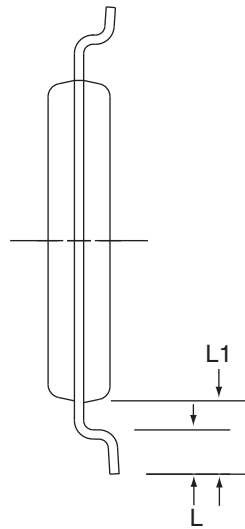
REV.

A

8A2 – TSSOP



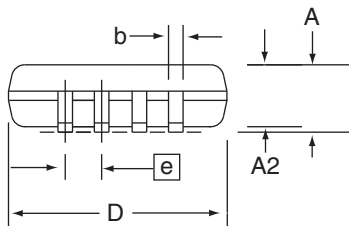
Top View



End View

COMMON DIMENSIONS
(Unit of Measure = mm)

| SYMBOL | MIN | NOM | MAX | NOTE |
|--------|----------|------|------|------|
| D | 2.90 | 3.00 | 3.10 | 2, 5 |
| E | 6.40 BSC | | | |
| E1 | 4.30 | 4.40 | 4.50 | 3, 5 |
| A | - | - | 1.20 | |
| A2 | 0.80 | 1.00 | 1.05 | |
| b | 0.19 | - | 0.30 | 4 |
| e | 0.65 BSC | | | |
| L | 0.45 | 0.60 | 0.75 | |
| L1 | 1.00 REF | | | |



Side View

- Notes:
1. This drawing is for general information only. Refer to JEDEC Drawing MO-153, Variation AA, for proper dimensions, tolerances, datums, etc.
 2. Dimension D does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15 mm (0.006 in) per side.
 3. Dimension E1 does not include inter-lead Flash or protrusions. Inter-lead Flash and protrusions shall not exceed 0.25 mm (0.010 in) per side.
 4. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall be 0.08 mm total in excess of the b dimension at maximum material condition. Dambar cannot be located on the lower radius of the foot. Minimum space between protrusion and adjacent lead is 0.07 mm.
 5. Dimension D and E1 to be determined at Datum Plane H.

5/30/02

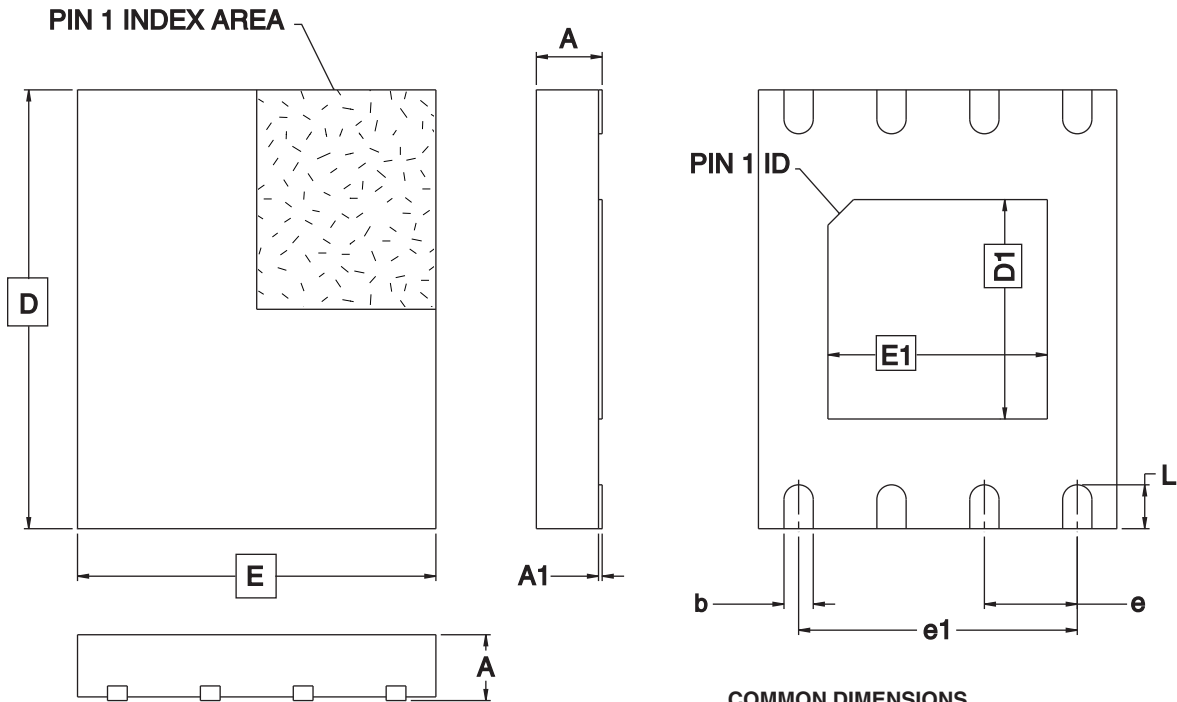
ATMEL 2325 Orchard Parkway
San Jose, CA 95131

TITLE
8A2, 8-lead, 4.4 mm Body, Plastic
Thin Shrink Small Outline Package (TSSOP)

DRAWING NO.
8A2

REV.
B

8Y7 – UTSAP



COMMON DIMENSIONS
(Unit of Measure = mm)

| SYMBOL | MIN | NOM | MAX | NOTE |
|--------|----------|------|------|------|
| A | – | – | 0.60 | |
| A1 | 0.00 | – | 0.05 | |
| D | 5.80 | 6.00 | 6.20 | |
| E | 4.70 | 4.90 | 5.10 | |
| D1 | 3.30 | 3.40 | 3.50 | |
| E1 | 3.90 | 4.00 | 4.10 | |
| b | 0.35 | 0.40 | 0.45 | |
| e | 1.27 TYP | | | |
| e1 | 3.81 REF | | | |
| L | 0.50 | 0.60 | 0.70 | |

10/13/05



1150 E. Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906

TITLE

8Y7, 8-lead (6.00 x 4.90 mm Body) Ultra-Thin SOIC Array Package (UTSAP) Y7

DRAWING NO.

8Y7

REV.

B

Revision History

| Doc. Rev. | Date | Comments |
|-----------|--------|---|
| 3368J | 6/2007 | Changed 8Y4 to 8Y7 package |
| 3368I | 3/2007 | Revision history implemented Removed Pb product offering |



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